




# Power MOSFETS


## DATASHEET

---

**LM1A039NAK8A**

N-Channel  
Enhancement Mode MOSFET

 Leadpower-semi CO., LTD.

 [sales@leadpower-semi.com](mailto:sales@leadpower-semi.com)

 (03) 6577339 FAX : (03) 6577229

 [www.leadpower-semi.com](http://www.leadpower-semi.com)

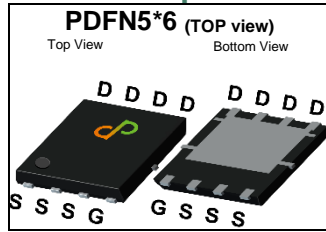


Quality Management Systems

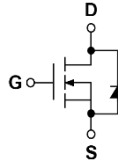
ISO 9001:2015 Certificate

## N-Channel Enhancement Mode MOSFET

### Pin Description



### Symbol



### Product Summary

Symbol	N-Channel	Unit
$V_{DSS}$	100	V
$R_{DS(ON)-Max}$	4.2	m $\Omega$
$I_D$	140	A

### Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

### Applications

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit

### Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM1A039NAK8A	PDFN5*6	Tape & Reel	5000 / Tape & Reel	1A039 □□□□□□

### Absolute Maximum Ratings (T<sub>J</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit	
$V_{DSS}$	Drain-Source Voltage	100	V	
$V_{GSS}$	Gate-Source Voltage	±20		
$T_J$	Maximum Junction Temperature	150	°C	
$T_{STG}$	Storage Temperature Range	-55 to 150	°C	
$I_{DM}^{①}$	Pulse Drain Current Tested	$T_c=25^\circ C$	350	A
$I_D$	Continuous Drain Current	$T_c=25^\circ C$	140	A
		$T_c=100^\circ C$	89	
$P_D$	Maximum Power Dissipation	$T_c=25^\circ C$	125	W
		$T_c=100^\circ C$	50	
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.1mH	45	A
$E_{AS}^{②}$	Avalanche Energy, Single pulse	L=0.1mH	101	mJ

### Thermal Characteristics

Symbol	Parameter	Rating	Unit	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	1	°C/W
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	Steady State	48	°C/W

Note ① : Max. current is limited by bonding wire

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz.

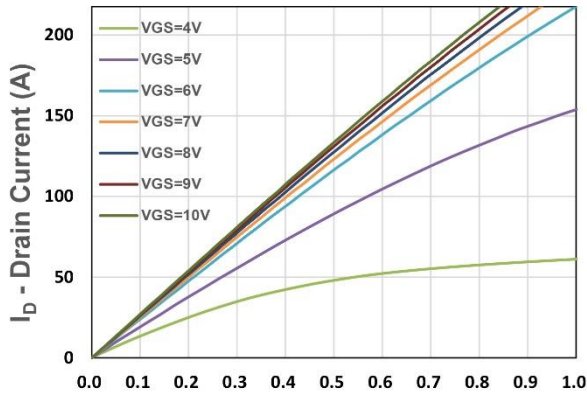
## N-Channel Electrical Characteristics (T<sub>J</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics</b>						
<b>BV<sub>DSS</sub></b>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250uA	100	-	-	V
<b>I<sub>DSS</sub></b>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	-	-	1	uA
<b>V<sub>GS(th)</sub></b>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA	1	2	3	V
<b>I<sub>GSS</sub></b>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>R<sub>DS(ON)</sub></b> <sup>④</sup>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =20A	-	3.5	4.2	mΩ
		V <sub>GS</sub> =4.5V, I <sub>DS</sub> =10A	-	5.1	6.6	
<b>g<sub>fs</sub></b>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>DS</sub> =10A	-	39	-	S
<b>Dynamic Characteristics</b> <sup>®</sup>						
<b>R<sub>G</sub></b>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, Freq.=1MHz	-	0.5	-	Ω
<b>C<sub>iss</sub></b>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =50V, Freq.=1MHz	-	4930	-	pF
<b>C<sub>oss</sub></b>	Output Capacitance					
<b>C<sub>rss</sub></b>	Reverse Transfer Capacitance					
<b>t<sub>d(ON)</sub></b>	Turn-on Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =25V, I <sub>D</sub> =1A, R <sub>GEN</sub> =3Ω	-	16	-	nS
<b>t<sub>r</sub></b>	Turn-on Rise Time					
<b>t<sub>d(OFF)</sub></b>	Turn-off Delay Time					
<b>t<sub>f</sub></b>	Turn-off Fall Time					
<b>Q<sub>g</sub></b>	Total Gate Charge	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =50V, I <sub>D</sub> =20A	-	47.5	-	nC
<b>Q<sub>g</sub></b>	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =50V, I <sub>D</sub> =20A	-	93.1	-	
<b>Q<sub>gs</sub></b>	Gate-Source Charge		-	20	-	
<b>Q<sub>gd</sub></b>	Gate-Drain Charge		-	21	-	
<b>Source-Drain Characteristics</b>						
<b>V<sub>SD</sub></b> <sup>④</sup>	Diode Forward Voltage	I <sub>SD</sub> =10A, V <sub>GS</sub> =0V	-	0.75	1.1	V
<b>t<sub>rr</sub></b>	Reverse Recovery Time	I <sub>F</sub> =10A, V <sub>R</sub> =50V	-	55	-	nS
<b>Q<sub>rr</sub></b>	Reverse Recovery Charge	dI <sub>F</sub> /dt=100A/μs	-	82	-	nC

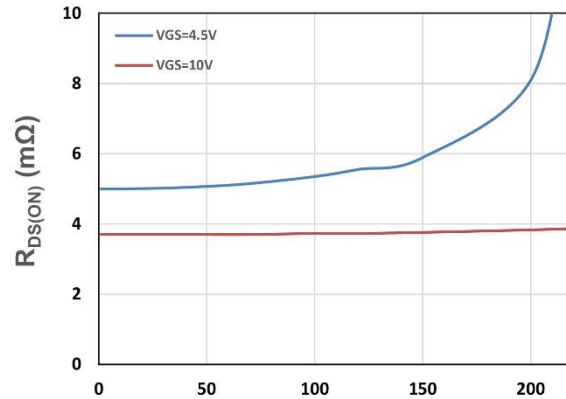
Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

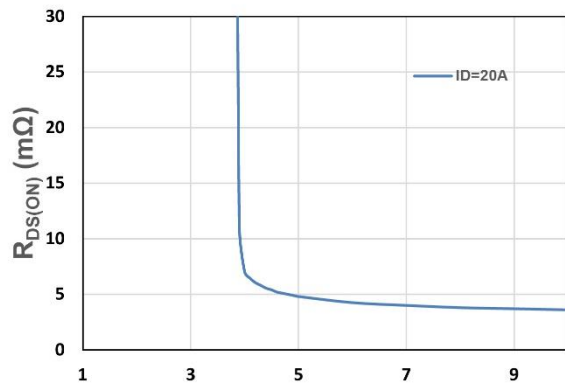
## N-Channel Typical Characteristics



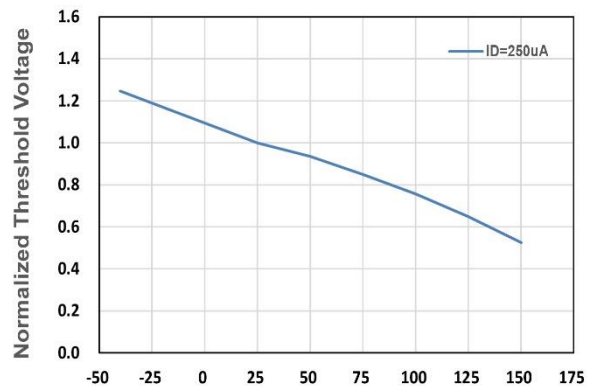
**V<sub>DS</sub> - Drain - Source Voltage (V)**  
**Figure 1. Output Characteristics**



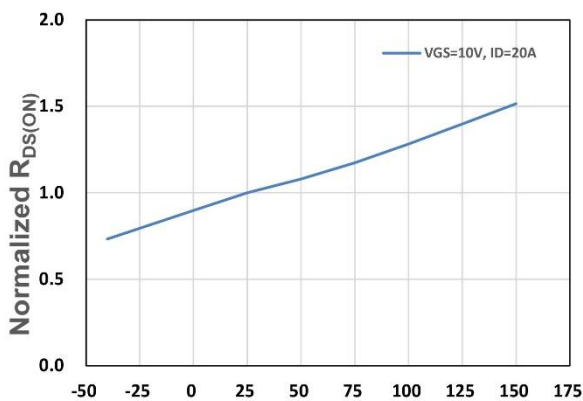
**I<sub>D</sub> - Drain Current (A)**  
**Figure 2. On-Resistance vs. ID**



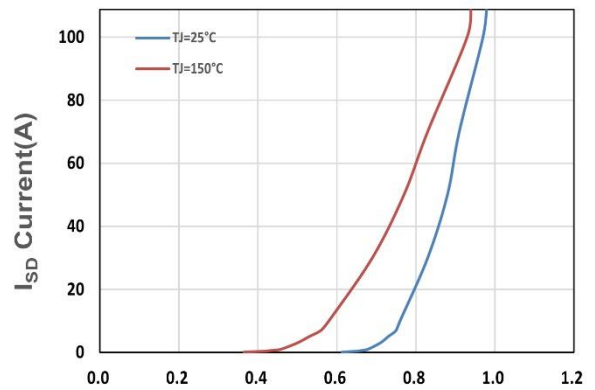
**V<sub>GS</sub> - Gate - Source Voltage (V)**  
**Figure 3. On-Resistance vs. VGS**



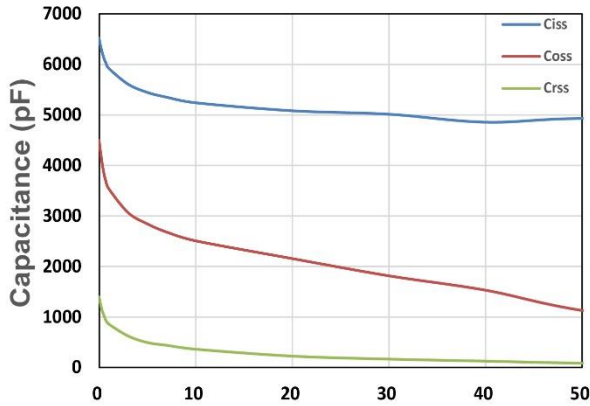
**T<sub>j</sub>, Junction Temperature(°C)**  
**Figure 4. Gate Threshold Voltage**



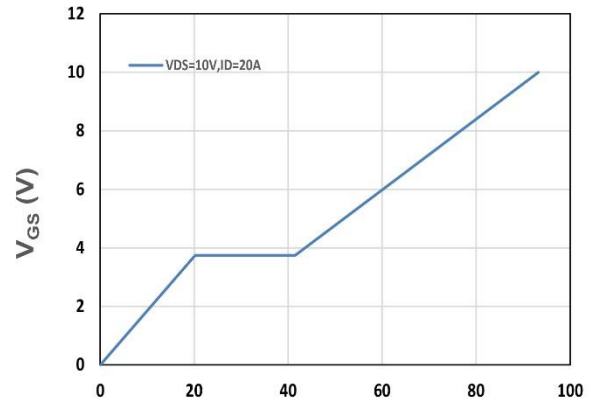
**T<sub>j</sub>, Junction Temperature(°C)**  
**Figure 5. Drain-Source On Resistance**



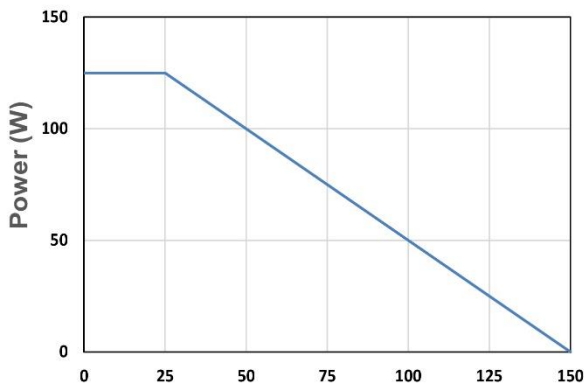
**V<sub>SD</sub>, Source-Drain Voltage(V)**  
**Figure 6. Source-Drain Diode Forward**



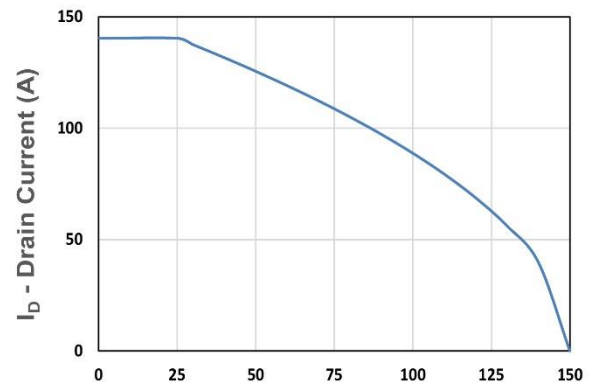
$V_{DS}$  - Drain - Source Voltage (V)  
Figure 7. Capacitance



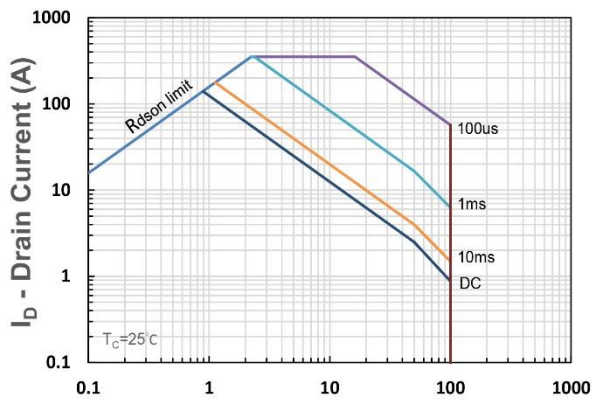
$Q_g$ , Total Gate Charge (nC)  
Figure 8. Gate Charge Characteristics



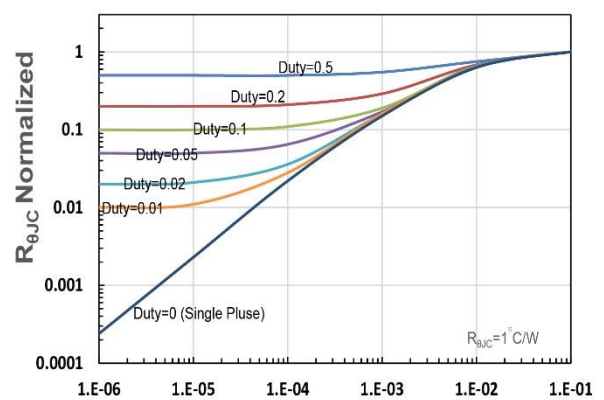
$T_c$  - Case Temperature ( $^{\circ}C$ )  
Figure 9. Power Dissipation



$T_c$  - Case Temperature ( $^{\circ}C$ )  
Figure 10. Drain Current



$V_{DS}$  - Drain-Source Voltage (V)  
Figure 11. Safe Operating Area



$t_1$ , Square Wave Pulse Duration(s)  
Figure 12.  $R_{\theta JC}$  Transient Thermal Impedance